



Features

- Adopt FRED chip
- Low forward Voltage drop
- Fast reverse recovery time
- High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability

Typical Applications

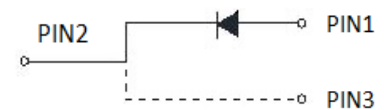
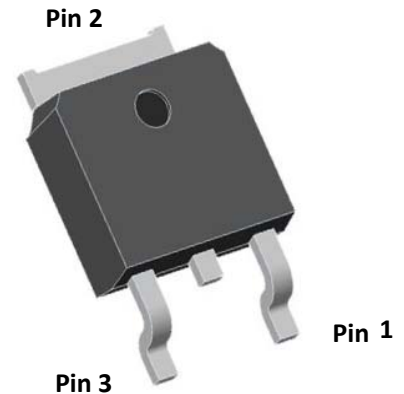
Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

Mechanical Data

- **Package:** TO-252
- Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** As marked

TYPE	V _{RSM} V	V _{RRM} V
MUR1560D	600	600

TO-252



A=Anode, C=Cathode, TAB=Cathode

■Maximum Ratings (T_j=25°C Unless otherwise specified)

Symbol	Test Conditions	Maximum Ratings	Unit	
I _{FRMS}	T _{VJ} =T _{VJM}	25	A	
I _{FAVM}	T _C =100°C; rectangular, d=0.5	15		
I _{FRM}	t _p <10us; rep. rating, pulse width limited by T _{VJM}	150		
I _{FSM}	T _{VJ} =45°C	t=10ms (50Hz), sine t=8.3ms (60Hz), sine	100 110	A
	T _{VJ} =150°C	t=10ms(50Hz), sine t=8.3ms(60Hz), sine	85 95	
I ² t	T _{VJ} =45°C	t=10ms (50Hz), sine t=8.3ms (60Hz), sine	50 50	A ² s
	T _{VJ} =150°C	t=10ms(50Hz), sine t=8.3ms(60Hz), sine	36 37	
T _{VJ} T _{VJM} T _{stg}		-40...+150 150 -40...+150	°C	
P _{tot}	T _C =25°C	62	W	
M _d	Mounting torque	0.4...0.6	Nm	
Weight		2	g	



■Electrical Characteristics

Symbol	Test Conditions	Characteristic Values		Unit
		typ.	max.	
I _R	T _{VJ} =25°C; V _R =V _{R_{RM}}		50	μA
	T _{VJ} =25°C; V _R =0.8·V _{R_{RM}}		25	μA
	T _{VJ} =125°C; V _R =0.8·V _{R_{RM}}		3	mA
V _F	I _F =15A; T _{VJ} =150°C T _{VJ} =25°C		1.5 1.7	V
V _{To}	For power-loss calculations only		1.12	V
r _T	T _{VJ} =T _{VJM}		23.2	mΩ
R _{thJC} R _{thCK} R _{thJA}		0.5	2 60	K/W
t _{rr}	I _F =1A; -di/dt=50A/us; V _R =30V; T _{VJ} =25°C	35	50	ns
I _{RM}	V _R =350V; I _F =15A; -di _F /dt=100A/us; L≤0.05μH; T _{VJ} =100°C	4	4.4	A

■Thermal Characteristics (T_j=25°C Unless otherwise specified)

PARAMETER		SYMBOL	UNIT	MUR1560D
Thermal Resistance	Between junction and case	R _{θJ-C}	°C/W	5.0
	Between junction and Air	R _{θJ-A}	°C/W	50

■Ordering Information (Example)

PREFERRED P/N	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
MUR1560D	Approximate 0.31	2500	2500	25000	Reel

■Characteristics (Typical)

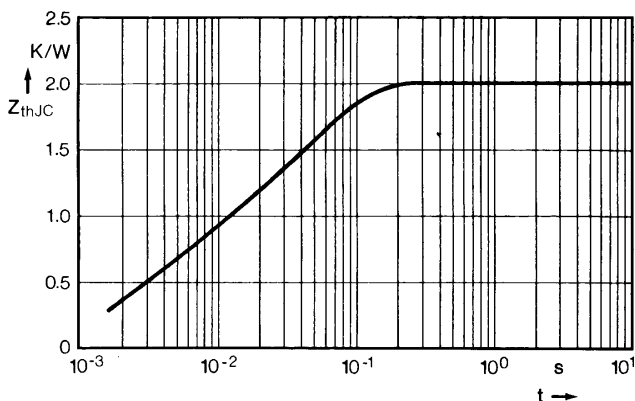


Fig. 7 Transient thermal impedance junction to case.

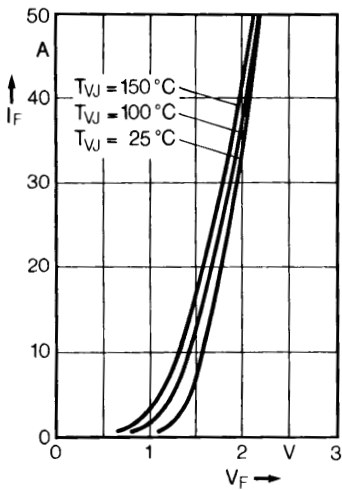

Characteristics (Typical)


Fig. 1 Forward current versus voltage drop.

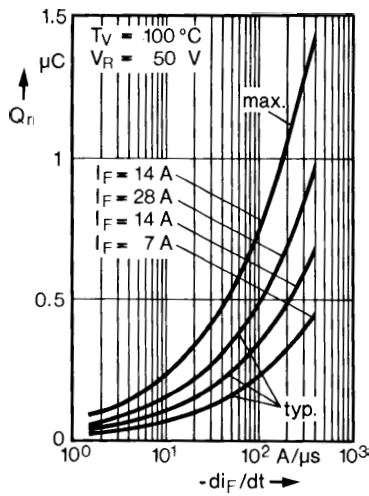
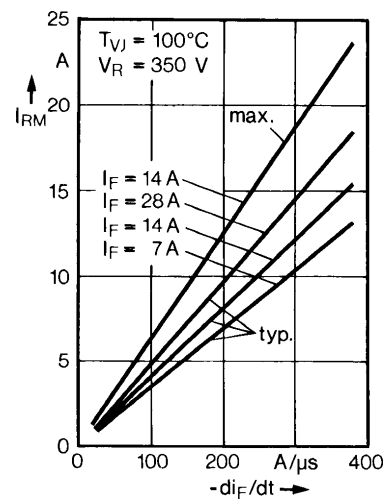
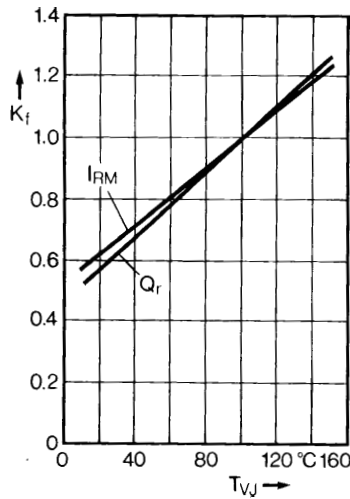

 Fig. 2 Recovery charge versus $-di_F/dt$.

 Fig. 3 Peak reverse current versus $-di_F/dt$.


Fig. 4 Dynamic parameters versus junction temperature.

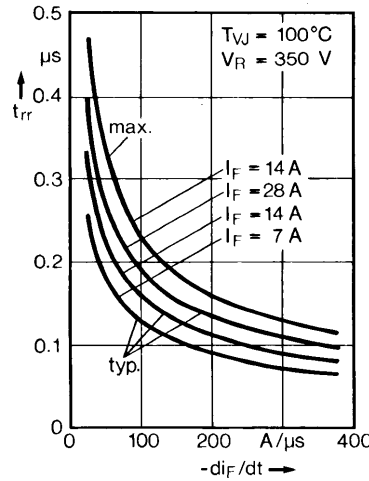
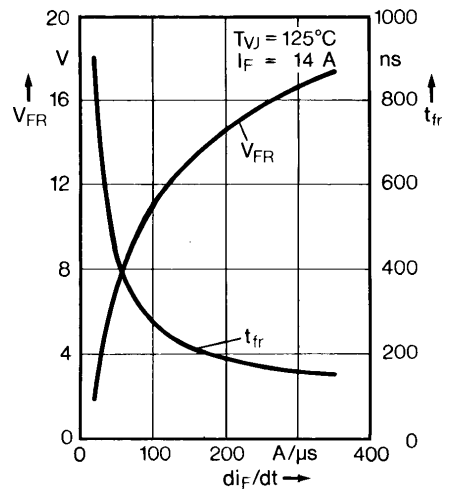
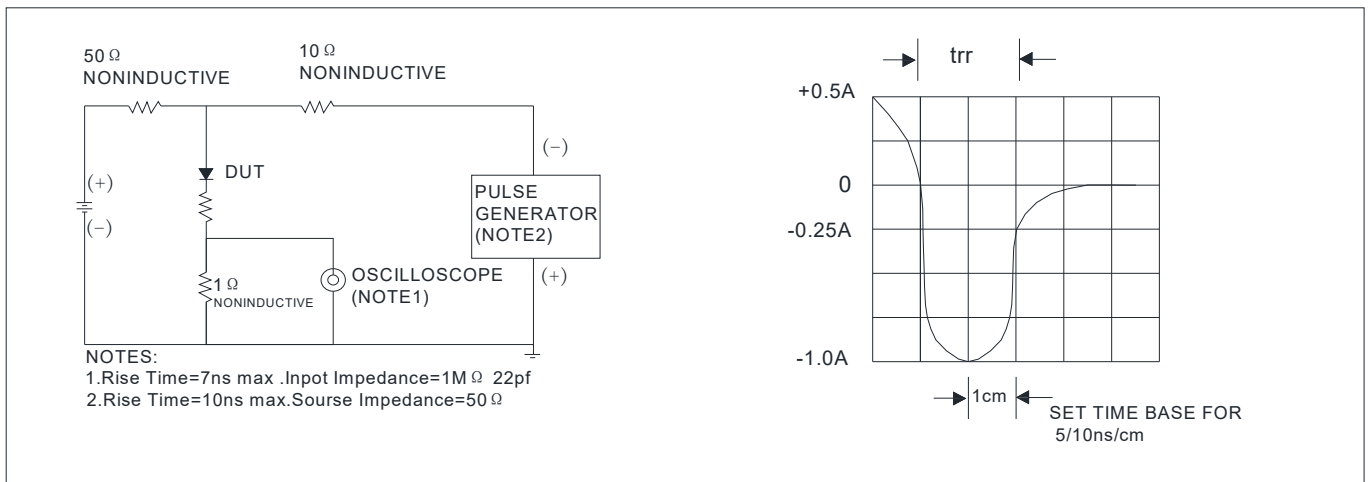
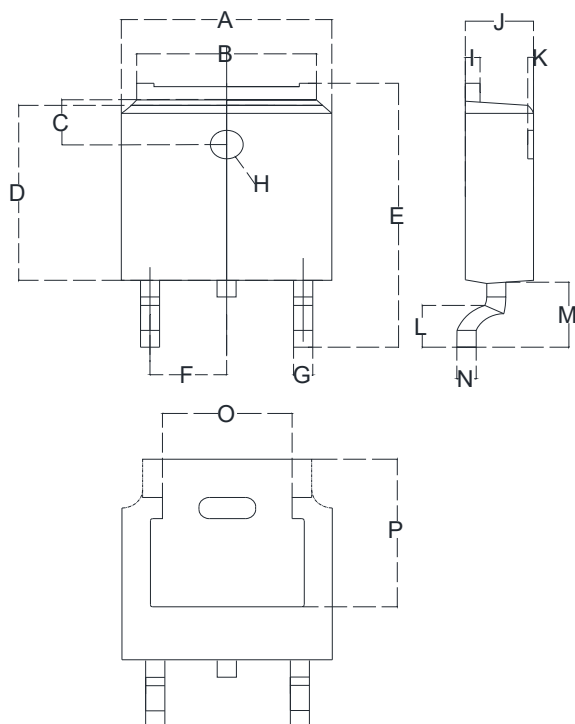

 Fig. 5 Recovery time versus $-di_F/dt$.

 Fig. 6 Peak forward voltage versus di_F/dt .

FIG.5: Diagram of circuit and Testing wave form of reverse recovery time


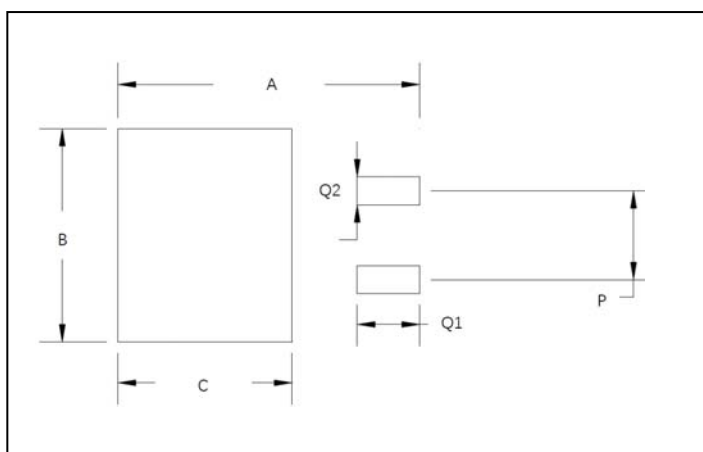
Outline Dimensions
MUR1560D


TO-252

单位: mm



TO-252		
Dim	Min	Max
A	6.500	6.700
B	5.100	5.460
C	1.400	1.800
D	6.000	6.200
E	10.000	10.400
F	2.166	2.366
G	0.660	0.860
H	Φ 1.050	Φ 1.350
I	0.460	0.580
J	2.200	2.400
K	0	0.300
L	0.890	2.290
M	2.730	3.080
N	0.430	0.580
O	4.20	4.95
P	5.15	5.45

Suggested Pad Layout


Dim	Millimeters
A	11.4
B	6.74
C	6.23
P	4.56
Q1	2.28
Q2	1.52

Package	Packing	Box Size L×W×H(mm)	Quantity(pcs/box)	Carton Size L×W×H(mm)	Quantity(pcs/carton)
TO-252	80pcs/Tube	560×178×35	4000	585×385×220	40000